

*Build Plate Informationen

Glue Stick

Cool Plate

Recommended Settings for Bambu Cool Plate

Please note that other slicer settings might need to be adjusted based on the model and filament requirements.

Material	Hotbed Temperature	Glue Stick Required	Upper Glass Cover Plate Removed?
PLA/PLA-CF/PLA-GF	35°C~45°C	Yes	Either
TPU	30°C~35°C	Yes	Either
PVA	35°C~45°C	Yes	Either

Engineering Plate

Recommended Settings for Bambu Engineering Plate

Please note that other slicer settings might need to be adjusted based on the model and filament requirements.

Material	Hotbed Temperature	Glue Stick Required	Upper Glass Cover Plate Removed?
TPU	35°C~35°C	Recommended	No
PETG	70°C~80°C	Recommended	Yes
ABS	100°C~110°C	Yes	No
PC/PC-CF	100°C~110°C	Yes	No
PA/PA-CF	100°C~120°C	Yes	No

High Temperatur Plate

Recommended Settings for Bambu High-Temperature Plate

Please note that other slicer settings might need to be adjusted based on the model and filament requirements.

Material	Hotbed Temperature	Glue Stick Required ?	Upper Glass Cover Plate Removed?
PLA/PLA-CF/PLA-GF	45°C~60°C	Recommended	Yes
ABS	90°C~100°C	Recommended	No
PETG	80°C	Yes	Yes
TPU	35°C	Recommended	Yes
ASA	90°C~100°C	Recommended	No
PVA	45°C~60°C	Recommended	Yes
PC/PC-CF	100°C~110°C	Yes	No
PA/PA-CF	100°C~110°C	Yes	No

PEI Plate

Recommended Settings

Please note that other slicer settings might need to be adjusted based on the model and filament requirements.

Material	Hotbed temperature	Glue Stick Required	Upper Glass Cover Plate Removed?
PLA/PLA-CF/PLA-GF	45°C~60°C	No	Yes
ABS	90°C~100°C	No	No
PETG	60°C~80°C	No	No
TPU	35°C~45°C	Yes	Yes
ASA	90°C~100°C	No	No
PVA	45°C~60°C	No	Yes
PC/PC-CF	90°C~110°C	Yes	No
PA/PA-CF	90°C~110°C	Yes	No

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